

100% Material Declaration Data Sheet

FTG256 Package for Spartan-6 FPGAs

Average Weight: 0.7170g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.01192	1.663
	Silicon	7440-21-3	100.00		0.01192	
Die Attach Material					0.002453	0.342
	Silver	7440-22-4	77.50		0.001901	
	Bismaleimide Monomer	Trade Secret	15.00		0.000368	
	Acrylate Monomer	Trade Secret	7.50		0.000184	
Mold Compound					0.384597	53.640
	Solid Epoxy Resin	Trade Secret	5.00		0.019230	
	Phenol Resin	Trade Secret	5.00		0.019230	
	Fused Silica	60676-86-0	87.45		0.336330	
	Metal Hydroxide	Trade Secret	2.00		0.007692	
	Carbon Black	1333-86-4	0.55		0.002115	
Substrate					0.184309	25.706
	Copper	7440-50-8	14.12		0.026027	
	Nickel	7440-02-0	6.23		0.011479	
	Gold	7440-57-5	1.24		0.002284	
Core	Epoxy Resin	Trade Secret	24.33		0.044844	
	Inorganic Filler	21645-51-2	9.12		0.016809	
	Fiberglass	65997-17-3	24.32		0.044825	
	Copper	7440-50-8	3.04		0.005603	
Solder Mask	Talc	14807-96-6	0.88		0.001622	
	Morpholine Derivative	Trade Secret	0.53		0.000973	
	Barium Sulfate	7727-43-7	7.74		0.014272	
	Silica	7631-86-9	0.18		0.000324	
	Dipropylene Glycol Monomethyl Ether	34590-94-8	4.58		0.008434	
	Epoxy Resin	85954-11-6	3.70		0.006812	
Gold Wire					0.009626	1.343
	Gold	7440-57-5	99.05		0.009534	
	Palladium	7440-05-3	0.95		0.000091	
	Calcium	7440-70-2	0.00		0.000000	

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Solder Balls					0.124093	17.307
	Tin	7440-31-5	96.50		0.119750	
	Silver	7440-22-4	3.00		0.003723	
	Copper	7440-50-8	0.50		0.000620	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
09/30/10	1.0	Initial Xilinx release.

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